

ABSTRACT

A first signal routing layer may be formed on a first surface of a printed circuit board (PCB). An array of interconnections may be formed on the first surface of the PCB, the array of interconnections comprising at least one padless via formed within the PCB, the at least one padless via extending from the first signal routing layer to at least one conductive plane and/or a second signal routing layer. The at least one padless via may be in electrical contact with the at least one conductive plane and/or a conductive trace on the second signal routing layer. A component may be attached to the PCB, with a solder interconnection between the at least one padless via and a contact pad on a bottom surface of the component. The component may be, for example, an electronic component such as a ball grid array (BGA) component or a leadless surface mount component.